



SOT1092-2(D)

plastic thermal enhanced very thin quad flat package; no leads; 0.1 dimple wettable flank; 36 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

14 March 2018

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN36
Package type industry code	HVQFN36
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	8-3-2018
Manufacturer package code	98ASA01212D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	6	-	mm
E	package width	-	-	6	-	mm
A	seated height	-	-	0.85	-	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	36	-	A/A



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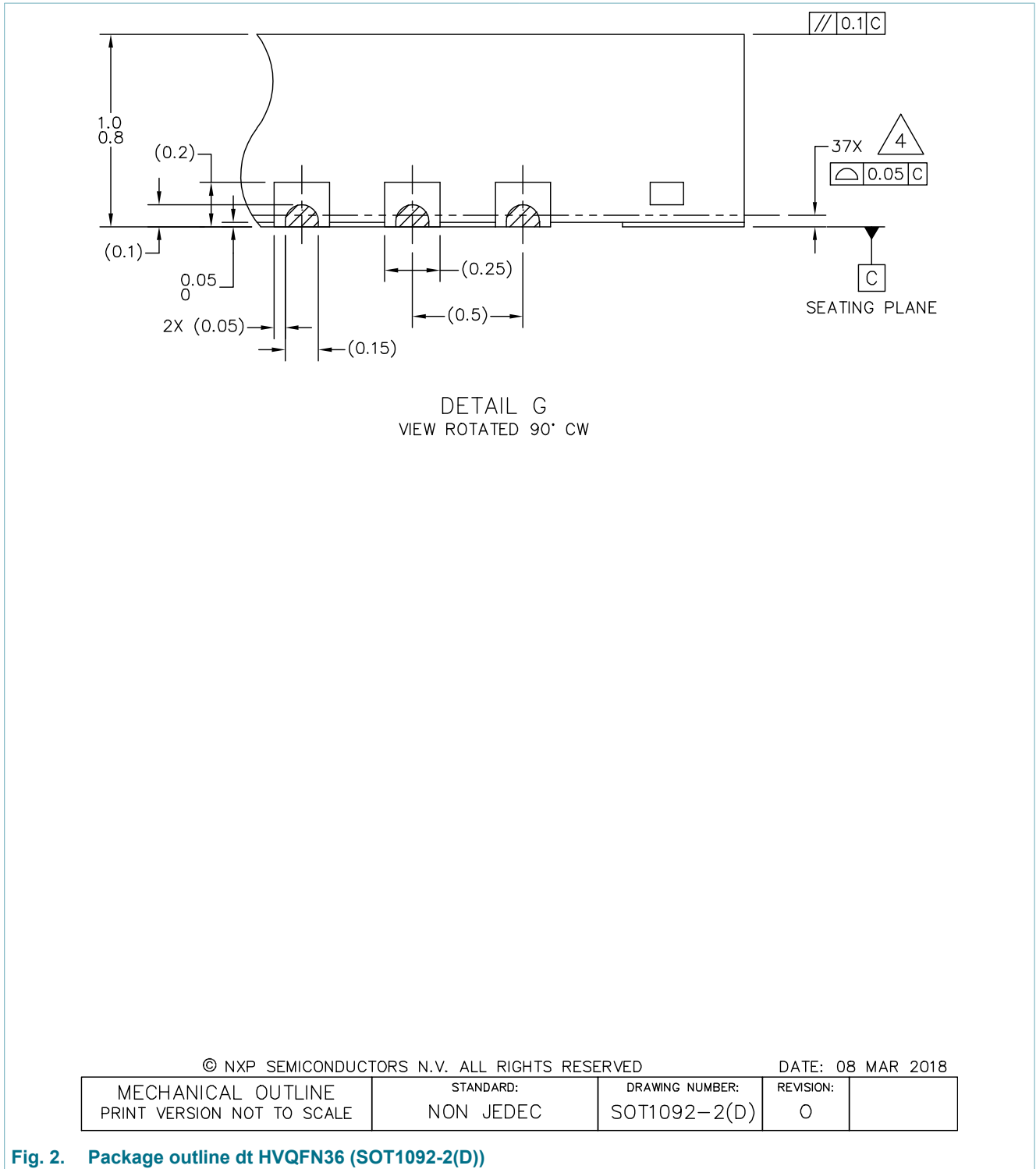


Fig. 2. Package outline dt HVQFN36 (SOT1092-2(D))

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.25 MM.

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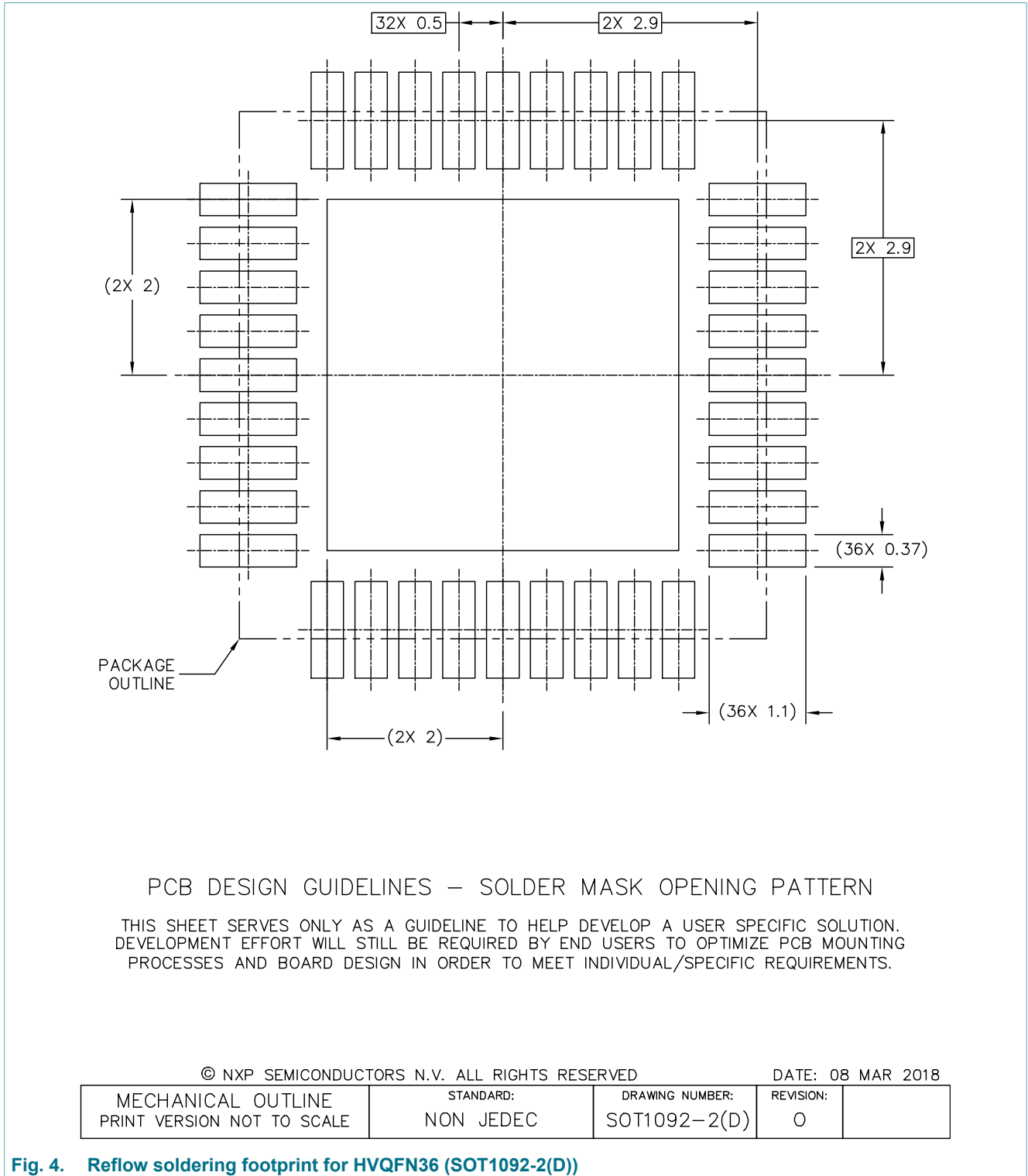
DATE: 08 MAR 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1092-2(D)	REVISION: 0	
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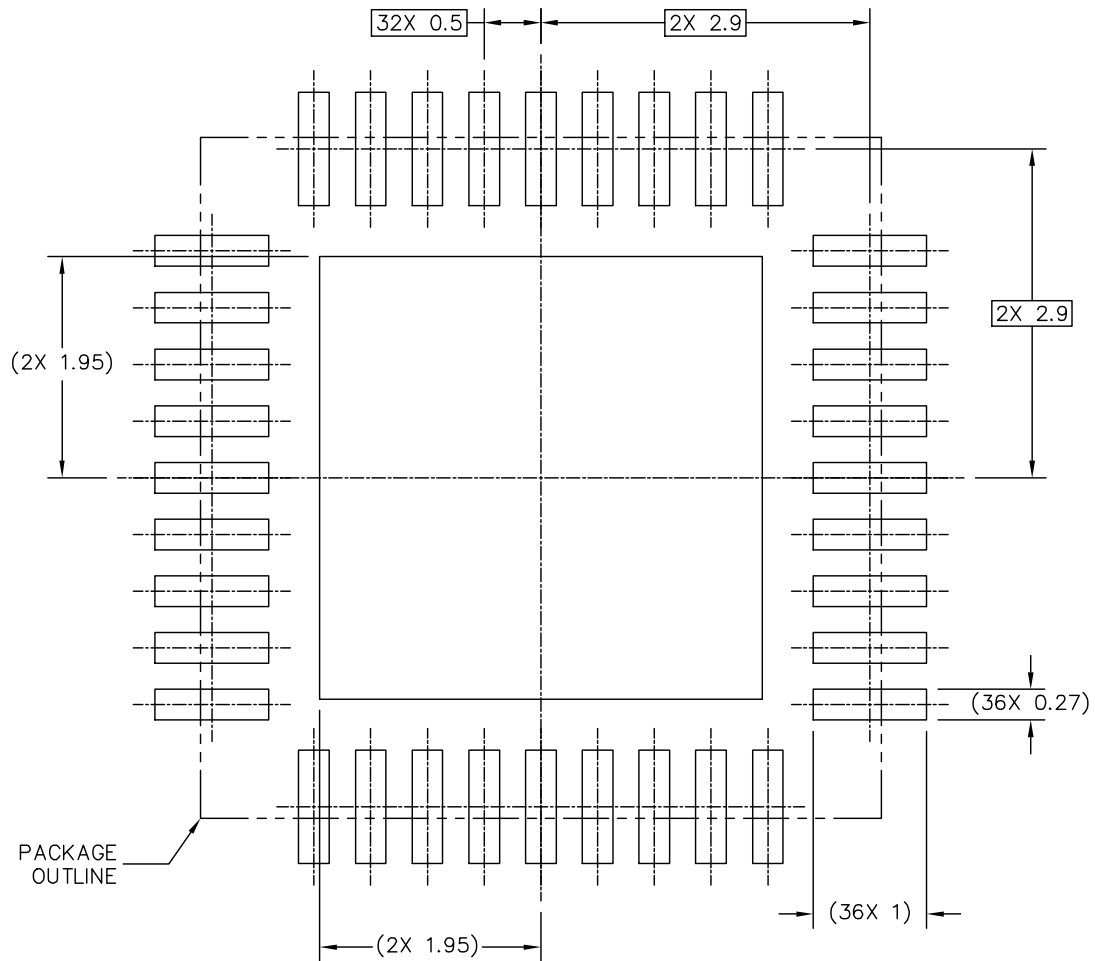
Fig. 3. Package outline note HVQFN36 (SOT1092-2(D))

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3. Soldering



plastic thermal enhanced very thin quad flat package; no leads; 0.1 dimple wettable flank; 36 terminals; 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body



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Fig. 5. Reflow soldering footprint part2 for HVQFN36 (SOT1092-2(D))

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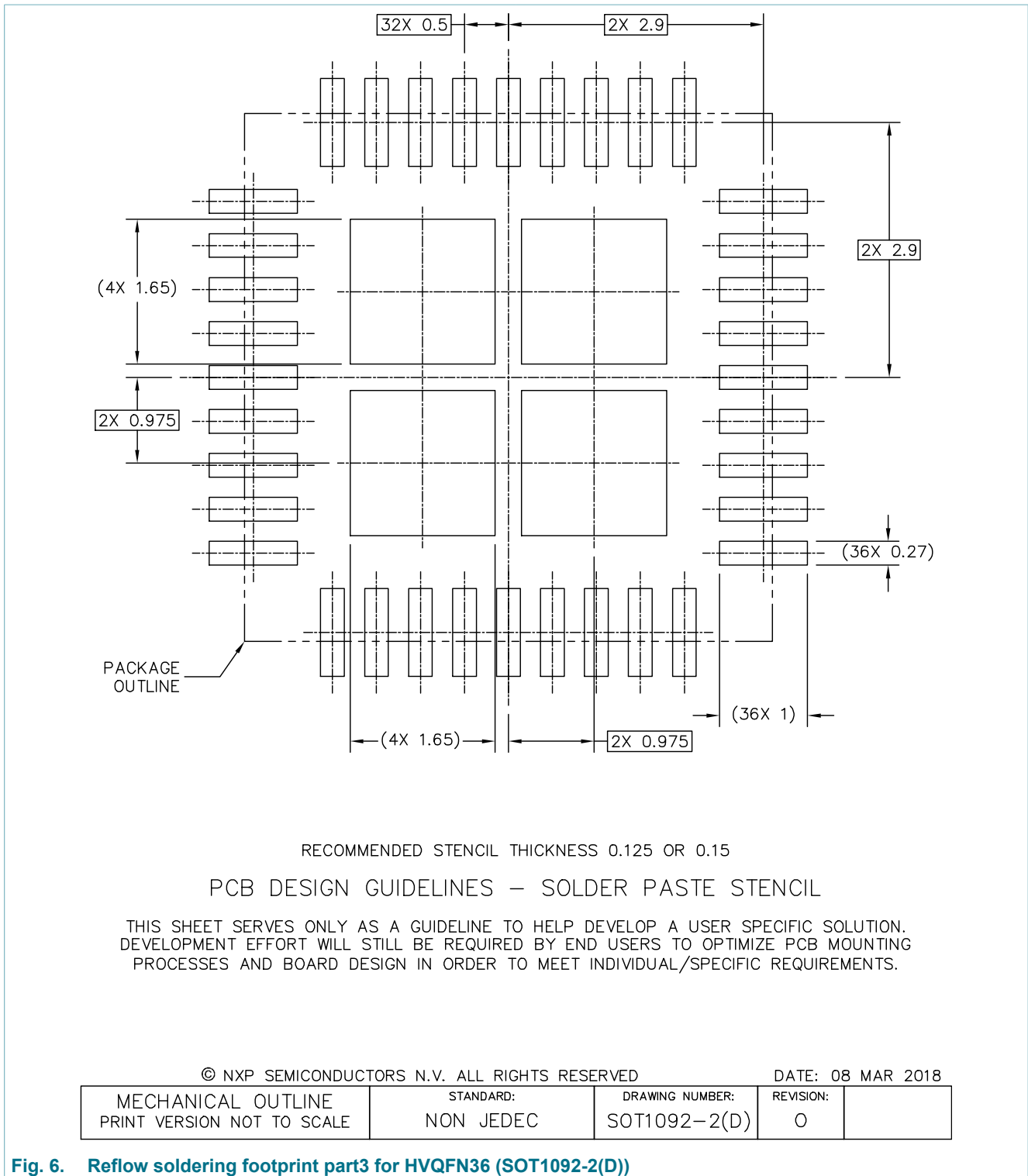


Fig. 6. Reflow soldering footprint part3 for HVQFN36 (SOT1092-2(D))

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4. Legal information

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